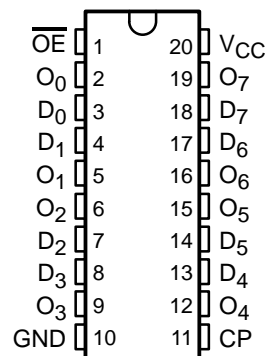


CY54FCT374T, CY74FCT374T 8-BIT REGISTERS WITH 3-STATE OUTPUTS

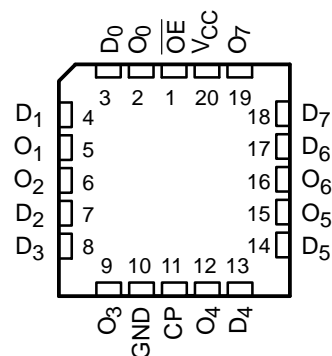
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- Function, Pinout, and Drive Compatible With FCT and F Logic
- Reduced V_{OH} (Typically = 3.3 V) Versions of Equivalent FCT Functions
- Edge-Rate Control Circuitry for Significantly Improved Noise Characteristics
- I_{off} Supports Partial-Power-Down Mode Operation
- Matched Rise and Fall Times
- Fully Compatible With TTL Input and Output Logic Levels
- ESD Protection Exceeds JESD 22
 - 2000-V Human-Body Model (A114-A)
 - 200-V Machine Model (A115-A)
 - 1000-V Charged-Device Model (C101)
- Edge-Triggered D-Type Inputs
- 250-MHz Typical Switching Rate
- CY54FCT374T
 - 32-mA Output Sink Current
 - 12-mA Output Source Current
- CY74FCT374T
 - 64-mA Output Sink Current
 - 32-mA Output Source Current
- 3-State Outputs

CY54FCT374T . . . D PACKAGE
CY74FCT374T . . . P, Q, OR SO PACKAGE
(TOP VIEW)



CY54FCT374T . . . L PACKAGE
(TOP VIEW)



description

The 'FCT374T devices are high-speed, low-power, octal D-type flip-flops, featuring separate D-type inputs for each flip-flop. These devices have 3-state outputs for bus-oriented applications. A buffered clock (CP) and output-enable (\overline{OE}) inputs are common to all flip-flops. The eight flip-flops in the 'FCT374T store the state of their individual D inputs that meet the setup-time and hold-time requirements on the low-to-high CP transition. When \overline{OE} is low, the contents of the eight flip-flops are available at the outputs. When \overline{OE} is high, the outputs are in the high-impedance state. The state of \overline{OE} does not affect the state of the flip-flops.

These devices are fully specified for partial-power-down applications using I_{off} . The I_{off} circuitry disables the outputs, preventing damaging current backflow through the device when it is powered down.



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.

 **TEXAS
INSTRUMENTS**

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On products compliant to MIL-PRF-38535, all parameters are tested unless otherwise noted. On all other products, production processing does not necessarily include testing of all parameters.

CY54FCT374T, CY74FCT374T

8-BIT REGISTERS

WITH 3-STATE OUTPUTS

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ORDERING INFORMATION

| TA | PACKAGE† | SPEED (ns) | ORDERABLE PART NUMBER | TOP-SIDE MARKING | |
|----------------|---------------|---------------|-----------------------|------------------|----------------|
| -40°C to 85°C | QSOP – Q | Tape and reel | 5.2 | CY74FCT374CTQCT | FCT374C |
| | SOIC – SO | Tube | 5.2 | CY74FCT374CTSOC | FCT374C |
| | | Tape and reel | 5.2 | CY74FCT374CTSOCT | |
| | DIP – P | Tube | 6.5 | CY74FCT374ATPC | CY74FCT374ATPC |
| | QSOP – Q | Tape and reel | 6.5 | CY74FCT374ATQCT | FCT374A |
| | SOIC – SO | Tube | 6.5 | CY74FCT374ATSOC | FCT374A |
| | | Tape and reel | 6.5 | CY74FCT374ATSOCT | |
| | QSOP – Q | Tape and reel | 10 | CY74FCT374TQCT | FCT374 |
| SOIC – SO | Tube | 10 | CY74FCT374TSOC | FCT374 | |
| | Tape and reel | 10 | CY74FCT374TSOCT | | |
| -55°C to 125°C | CDIP – D | Tube | 6.2 | CY54FCT374CTDMB | |
| | LCC – L | Tube | 6.2 | CY54FCT374CTLMB | |
| | CDIP – D | Tube | 7.2 | CY54FCT374ATDMB | |
| | LCC – L | Tube | 7.2 | CY54FCT374ATLMB | |
| | CDIP – D | Tube | 11 | CY54FCT374TDMB | |
| | LCC – L | Tube | 11 | CY54FCT374TLMB | |

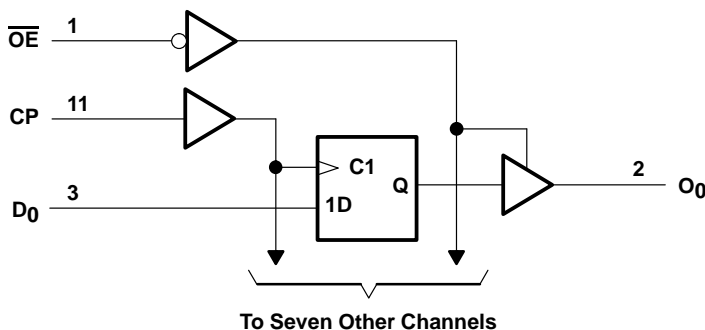
† Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.

FUNCTION TABLE

| INPUTS | | | OUTPUT |
|--------|----|-----------------|--------|
| D | CP | \overline{OE} | O |
| H | ↑ | L | H |
| L | ↑ | L | L |
| X | X | H | Z |

H = High logic level, L = Low logic level,
 X = Don't care, Z = High-impedance state,
 ↑ = Low-to-high clock transition

logic diagram (positive logic)



CY54FCT374T, CY74FCT374T
8-BIT REGISTERS
WITH 3-STATE OUTPUTS

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absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

| | |
|--|----------------|
| Supply voltage range to ground potential | –0.5 V to 7 V |
| DC input voltage range | –0.5 V to 7 V |
| DC output voltage range | –0.5 V to 7 V |
| DC output current (maximum sink current/pin) | 120 mA |
| Package thermal impedance, θ_{JA} (see Note 1): P package | 69°C/W |
| Q package | 68°C/W |
| SO package | 58°C/W |
| Ambient temperature range with power applied, T_A | –65°C to 135°C |
| Storage temperature range, T_{Stg} | –65°C to 150°C |

† Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTE 1: The package thermal impedance is calculated in accordance with JESD 51-7.

recommended operating conditions (see Note 2)

| | CY54FCT374T | | | CY74FCT374T | | | UNIT |
|--------------------------------------|-------------|-----|-----|-------------|-----|------|------|
| | MIN | NOM | MAX | MIN | NOM | MAX | |
| V_{CC} Supply voltage | 4.5 | 5 | 5.5 | 4.75 | 5 | 5.25 | V |
| V_{IH} High-level input voltage | 2 | | | 2 | | | V |
| V_{IL} Low-level input voltage | 0.8 | | | 0.8 | | | V |
| I_{OH} High-level output current | –12 | | | –32 | | | mA |
| I_{OL} Low-level output current | 32 | | | 64 | | | mA |
| T_A Operating free-air temperature | –55 125 | | | –40 85 | | | °C |

NOTE 2: All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation.

CY54FCT374T, CY74FCT374T

8-BIT REGISTERS

WITH 3-STATE OUTPUTS

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electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

| PARAMETER | TEST CONDITIONS | CY54FCT374T | | | CY74FCT374T | | | UNIT |
|-------------------|--|--------------------------|------|------|-------------|------|------|------|
| | | MIN | TYP† | MAX | MIN | TYP† | MAX | |
| V _{IK} | V _{CC} = 4.5 V, I _{IN} = -18 mA | | -0.7 | -1.2 | | | | V |
| | V _{CC} = 4.75 V, I _{IN} = -18 mA | | | | | -0.7 | -1.2 | |
| V _{OH} | V _{CC} = 4.5 V, I _{OH} = -12 mA | 2.4 | 3.3 | | | | | V |
| | V _{CC} = 4.75 V | I _{OH} = -32 mA | | | 2 | | | |
| | | I _{OH} = -15 mA | | | | 2.4 | 3.3 | |
| V _{OL} | V _{CC} = 4.5 V, I _{OL} = 32 mA | | 0.3 | 0.55 | | | | V |
| | V _{CC} = 4.75 V, I _{OL} = 64 mA | | | | | 0.3 | 0.55 | |
| V _{hys} | All inputs | | 0.2 | | | 0.2 | | V |
| I _I | V _{CC} = 5.5 V, V _{IN} = V _{CC} | | | 5 | | | | μA |
| | V _{CC} = 5.25 V, V _{IN} = V _{CC} | | | | | | 5 | |
| I _{IH} | V _{CC} = 5.5 V, V _{IN} = 2.7 V | | | ±1 | | | | μA |
| | V _{CC} = 5.25 V, V _{IN} = 2.7 V | | | | | | ±1 | |
| I _{IL} | V _{CC} = 5.5 V, V _{IN} = 0.5 V | | | ±1 | | | | μA |
| | V _{CC} = 5.25 V, V _{IN} = 0.5 V | | | | | | ±1 | |
| I _{off} | V _{CC} = 0 V, V _{OUT} = 4.5 V | | | ±1 | | | ±1 | μA |
| I _{OS} ‡ | V _{CC} = 5.5 V, V _{OUT} = 0 V | -60 | -120 | -225 | | | | mA |
| | V _{CC} = 5.25 V, V _{OUT} = 0 V | | | | -60 | -120 | -225 | |
| I _{OZH} | V _{CC} = 5.5 V, V _{IN} = 2.7 V | | | 10 | | | | μA |
| | V _{CC} = 5.25 V, V _{IN} = 2.7 V | | | | | | 10 | |
| I _{OZL} | V _{CC} = 5.5 V, V _{IN} = 0.5 V | | | -10 | | | | μA |
| | V _{CC} = 5.25 V, V _{IN} = 0.5 V | | | | | | -10 | |
| I _{CC} | V _{CC} = 5.5 V, V _{IN} ≤ 0.2 V, V _{IN} ≥ V _{CC} - 0.2 V | | 0.1 | 0.2 | | | | mA |
| | V _{CC} = 5.25 V, V _{IN} ≤ 0.2 V, V _{IN} ≥ V _{CC} - 0.2 V | | | | | 0.1 | 0.2 | |
| ΔI _{CC} | V _{CC} = 5.5 V, V _{IN} = 3.4 V§, f ₁ = 0, Outputs open | | 0.5 | 2 | | | | mA |
| | V _{CC} = 5.25 V, V _{IN} = 3.4 V§, f ₁ = 0, Outputs open | | | | | 0.5 | 2 | |

† Typical values are at V_{CC} = 5 V, T_A = 25°C.

‡ Not more than one output should be shorted at a time. Duration of short should not exceed one second. The use of high-speed test apparatus and/or sample-and-hold techniques are preferable to minimize internal chip heating and more accurately reflect operational values. Otherwise, prolonged shorting of a high output can raise the chip temperature well above normal and cause invalid readings in other parametric tests. In any sequence of parameter tests, I_{OS} tests should be performed last.

§ Per TTL-driven input (V_{IN} = 3.4 V); all other inputs at V_{CC} or GND



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8-BIT REGISTERS
WITH 3-STATE OUTPUTS

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electrical characteristics over recommended operating free-air temperature range (unless otherwise noted) (continued)

| PARAMETER | TEST CONDITIONS | | CY54FCT374T | | CY74FCT374T | | UNIT | | |
|----------------------|--|--|--|------|-------------|------|------|------------|-----|
| | | | MIN | TYP† | MAX | MIN | | TYP† | MAX |
| I_{CCD}^{\ddagger} | $V_{CC} = 5.5\text{ V}$, Outputs open, One bit switching at 50% duty cycle, $\overline{OE} = \text{GND}$, $V_{IN} \leq 0.2\text{ V}$ or $V_{IN} \geq V_{CC} - 0.2\text{ V}$ | | | 0.06 | 0.12 | | | mA/ MHz | |
| | $V_{CC} = 5.25\text{ V}$, Outputs open, One bit switching at 50% duty cycle, $\overline{OE} = \text{GND}$, $V_{IN} \leq 0.2\text{ V}$ or $V_{IN} \geq V_{CC} - 0.2\text{ V}$ | | | | | 0.06 | 0.12 | | |
| I_C | $V_{CC} = 5.5\text{ V}$, $f_0 = 10\text{ MHz}$, Outputs open, $\overline{OE} = \text{GND}$ | One bit switching at $f_1 = 5\text{ MHz}$ at 50% duty cycle | $V_{IN} \leq 0.2\text{ V}$ or $V_{IN} \geq V_{CC} - 0.2\text{ V}$ | 0.7 | 1.4 | | | mA | |
| | | | $V_{IN} = 3.4\text{ V}$ or GND | 1.2 | 3.4 | | | | |
| | | Eight bits switching at $f_1 = 2.5\text{ MHz}$ at 50% duty cycle | $V_{IN} \leq 0.2\text{ V}$ or $V_{IN} \geq V_{CC} - 0.2\text{ V}$ | 1.6 | 3.2 | | | | |
| | | | $V_{IN} = 3.4\text{ V}$ or GND | 3.9 | 12.2 | | | | |
| | $V_{CC} = 5.25\text{ V}$, $f_0 = 10\text{ MHz}$, Outputs open, $\overline{OE} = \text{GND}$ | One bit switching at $f_1 = 5\text{ MHz}$ at 50% duty cycle | $V_{IN} \leq 0.2\text{ V}$ or $V_{IN} \geq V_{CC} - 0.2\text{ V}$ | | | 0.7 | 1.4 | | |
| | | | $V_{IN} = 3.4\text{ V}$ or GND | | | 1.2 | 3.4 | | |
| | | Eight bits switching at $f_1 = 2.5\text{ MHz}$ at 50% duty cycle | $V_{IN} \leq 0.2\text{ V}$ or $V_{IN} \geq V_{CC} - 0.2\text{ V}$ | | | 1.6 | 3.2 | | |
| | | | $V_{IN} = 3.4\text{ V}$ or GND | | | 3.9 | 12.2 | | |
| C_i | | | | 5 | 10 | | 5 | 10 | pF |
| C_o | | | | 9 | 12 | | 9 | 12 | pF |

† Typical values are at $V_{CC} = 5\text{ V}$, $T_A = 25^\circ\text{C}$.

‡ This parameter is derived for use in total power-supply calculations.

$I_C = I_{CC} + \Delta I_{CC} \times D_H \times N_T + I_{CCD} (f_0/2 + f_1 \times N_1)$

Where:

I_C = Total supply current

I_{CC} = Power-supply current with CMOS input levels

ΔI_{CC} = Power-supply current for a TTL high input ($V_{IN} = 3.4\text{ V}$)

D_H = Duty cycle for TTL inputs high

N_T = Number of TTL inputs at D_H

I_{CCD} = Dynamic current caused by an input transition pair (HLH or LHL)

f_0 = Clock frequency for registered devices, otherwise zero

f_1 = Input signal frequency

N_1 = Number of inputs changing at f_1

All currents are in milliamperes and all frequencies are in megahertz.

|| Values for these conditions are examples of the I_{CC} formula.



CY54FCT374T, CY74FCT374T

8-BIT REGISTERS

WITH 3-STATE OUTPUTS

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timing requirements over recommended operating free-air temperature range (unless otherwise noted) (see Figure 1)

| | | CY54FCT374T | | CY54FCT374AT | | CY54FCT374CT | | UNIT |
|-----------------|--------------------------------|-------------|-----|--------------|-----|--------------|-----|------|
| | | MIN | MAX | MIN | MAX | MIN | MAX | |
| t _w | Pulse duration, CP high or low | 7 | | 6 | | 6 | | ns |
| t _{su} | Setup time, data before CP↑ | 2 | | 2 | | 2 | | ns |
| t _h | Hold time, data after CP↑ | 1.5 | | 1.5 | | 1.5 | | ns |

timing requirements over recommended operating free-air temperature range (unless otherwise noted) (see Figure 1)

| | | CY74FCT374T | | CY74FCT374AT | | CY74FCT374CT | | UNIT |
|-----------------|--------------------------------|-------------|-----|--------------|-----|--------------|-----|------|
| | | MIN | MAX | MIN | MAX | MIN | MAX | |
| t _w | Pulse duration, CP high or low | 7 | | 5 | | 5 | | ns |
| t _{su} | Setup time, data before CP↑ | 2 | | 2 | | 2 | | ns |
| t _h | Hold time, data after CP↑ | 1.5 | | 1.5 | | 1.5 | | ns |

switching characteristics over operating free-air temperature range (see Figure 1)

| PARAMETER | FROM (INPUT) | TO (OUTPUT) | CY54FCT374T | | CY54FCT374AT | | CY54FCT374CT | | UNIT |
|------------------|-----------------|-------------|-------------|-----|--------------|-----|--------------|-----|------|
| | | | MIN | MAX | MIN | MAX | MIN | MAX | |
| t _{PLH} | CP | O | 2 | 11 | 2 | 7.2 | 2 | 6.2 | ns |
| t _{PHL} | | | 2 | 11 | 2 | 7.2 | 2 | 6.2 | |
| t _{PZH} | \overline{OE} | O | 1.5 | 14 | 1.5 | 7.5 | 1.5 | 6.2 | ns |
| t _{PZL} | | | 1.5 | 14 | 1.5 | 7.5 | 1.5 | 6.2 | |
| t _{PHZ} | \overline{OE} | O | 1.5 | 8 | 1.5 | 6.5 | 1.5 | 5.7 | ns |
| t _{PLZ} | | | 1.5 | 8 | 1.5 | 6.5 | 1.5 | 5.7 | |

switching characteristics over operating free-air temperature range (see Figure 1)

| PARAMETER | FROM (INPUT) | TO (OUTPUT) | CY74FCT374T | | CY74FCT374AT | | CY74FCT374CT | | UNIT |
|------------------|-----------------|-------------|-------------|------|--------------|-----|--------------|-----|------|
| | | | MIN | MAX | MIN | MAX | MIN | MAX | |
| t _{PLH} | CP | O | 2 | 10 | 2 | 6.5 | 2 | 5.2 | ns |
| t _{PHL} | | | 2 | 10 | 2 | 6.5 | 2 | 5.2 | |
| t _{PZH} | \overline{OE} | O | 1.5 | 12.5 | 1.5 | 6.5 | 1.5 | 5.5 | ns |
| t _{PZL} | | | 1.5 | 12.5 | 1.5 | 6.5 | 1.5 | 5.5 | |
| t _{PHZ} | \overline{OE} | O | 1.5 | 8 | 1.5 | 5.5 | 1.5 | 5 | ns |
| t _{PLZ} | | | 1.5 | 8 | 1.5 | 5.5 | 1.5 | 5 | |

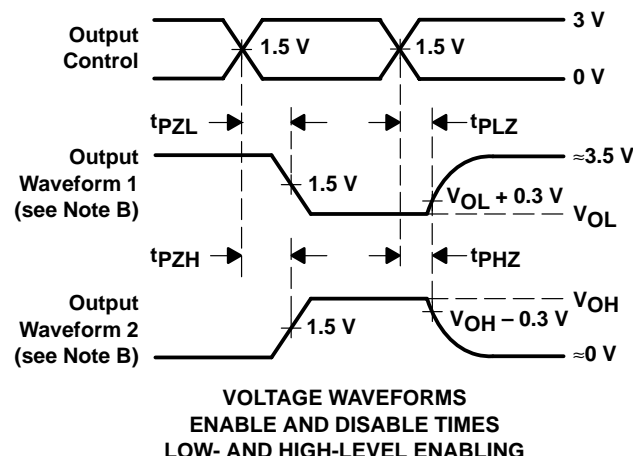
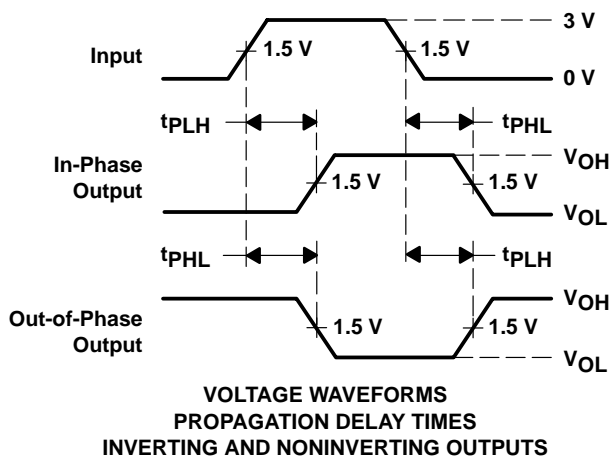
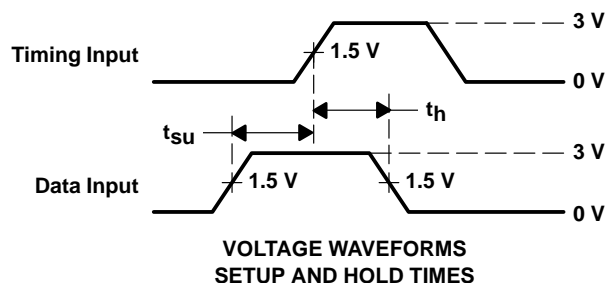
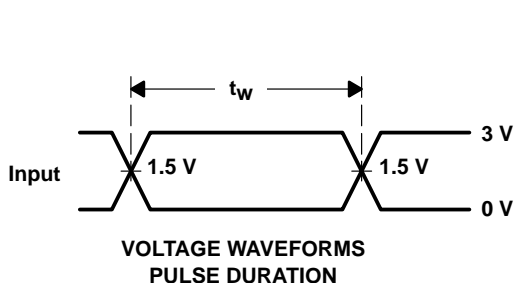


PARAMETER MEASUREMENT INFORMATION



LOAD CIRCUIT FOR TOTEM-POLE OUTPUTS

LOAD CIRCUIT FOR 3-STATE OUTPUTS



- NOTES: A. C_L includes probe and jig capacitance.
 B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
 C. The outputs are measured one at a time with one input transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms

PACKAGING INFORMATION

| Orderable Device | Status ⁽¹⁾ | Package Type | Package Drawing | Pins | Package Qty | Eco Plan ⁽²⁾ | Lead/ Ball Finish | MSL Peak Temp ⁽³⁾ | Samples (Requires Login) |
|-------------------|-----------------------|--------------|-----------------|------|-------------|-------------------------|----------------------|------------------------------|-----------------------------|
| 5962-9221802M2A | ACTIVE | LCCC | FK | 20 | 1 | TBD | Call TI | Call TI | |
| 5962-9221802MRA | ACTIVE | CDIP | J | 20 | 1 | TBD | Call TI | Call TI | |
| 5962-9221804M2A | ACTIVE | LCCC | FK | 20 | 1 | TBD | Call TI | Call TI | |
| 5962-9221804MRA | ACTIVE | CDIP | J | 20 | 1 | TBD | Call TI | Call TI | |
| 5962-9221806M2A | ACTIVE | LCCC | FK | 20 | 1 | TBD | Call TI | Call TI | |
| 5962-9221806MRA | ACTIVE | CDIP | J | 20 | 1 | TBD | A42 | N / A for Pkg Type | |
| 5962-9222203M2A | ACTIVE | LCCC | FK | 20 | 1 | TBD | Call TI | Call TI | |
| 5962-9222203MRA | ACTIVE | CDIP | J | 20 | 1 | TBD | A42 | N / A for Pkg Type | |
| 5962-9222205MRA | ACTIVE | CDIP | J | 20 | 1 | TBD | A42 | N / A for Pkg Type | |
| CY54FCT374ATDMB | ACTIVE | CDIP | J | 20 | 1 | TBD | A42 | N / A for Pkg Type | |
| CY54FCT374ATLMB | ACTIVE | LCCC | FK | 20 | 1 | TBD | POST-PLATE | N / A for Pkg Type | |
| CY54FCT374CTLMB | ACTIVE | LCCC | FK | 20 | 1 | TBD | POST-PLATE | N / A for Pkg Type | |
| CY54FCT374TDMB | ACTIVE | CDIP | J | 20 | 1 | TBD | A42 | N / A for Pkg Type | |
| CY54FCT374TLMB | ACTIVE | LCCC | FK | 20 | 1 | TBD | POST-PLATE | N / A for Pkg Type | |
| CY54FCT574ATLMB | ACTIVE | LCCC | FK | 20 | 1 | TBD | POST-PLATE | N / A for Pkg Type | |
| CY74FCT374ATPC | ACTIVE | PDIP | N | 20 | 20 | Pb-Free (RoHS) | CU NIPDAU | N / A for Pkg Type | |
| CY74FCT374ATPCE4 | ACTIVE | PDIP | N | 20 | 20 | Pb-Free (RoHS) | CU NIPDAU | N / A for Pkg Type | |
| CY74FCT374ATQCT | ACTIVE | SSOP | DBQ | 20 | 2500 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-2-260C-1 YEAR | |
| CY74FCT374ATQCTE4 | ACTIVE | SSOP | DBQ | 20 | 2500 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-2-260C-1 YEAR | |
| CY74FCT374ATQCTG4 | ACTIVE | SSOP | DBQ | 20 | 2500 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-2-260C-1 YEAR | |
| CY74FCT374ATSOC | ACTIVE | SOIC | DW | 20 | 25 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | |
| CY74FCT374ATSOCE4 | ACTIVE | SOIC | DW | 20 | 25 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | |
| CY74FCT374ATSOCG4 | ACTIVE | SOIC | DW | 20 | 25 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | |
| CY74FCT374ATSOCT | ACTIVE | SOIC | DW | 20 | 2000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | |

| Orderable Device | Status ⁽¹⁾ | Package Type | Package Drawing | Pins | Package Qty | Eco Plan ⁽²⁾ | Lead/ Ball Finish | MSL Peak Temp ⁽³⁾ | Samples (Requires Login) |
|--------------------|-----------------------|--------------|-----------------|------|-------------|-------------------------|----------------------|------------------------------|-----------------------------|
| CY74FCT374ATSOCTE4 | ACTIVE | SOIC | DW | 20 | 2000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | |
| CY74FCT374ATSOCTG4 | ACTIVE | SOIC | DW | 20 | 2000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | |
| CY74FCT374CTQCT | ACTIVE | SSOP | DBQ | 20 | 2500 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-2-260C-1 YEAR | |
| CY74FCT374CTQCTE4 | ACTIVE | SSOP | DBQ | 20 | 2500 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-2-260C-1 YEAR | |
| CY74FCT374CTQCTG4 | ACTIVE | SSOP | DBQ | 20 | 2500 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-2-260C-1 YEAR | |
| CY74FCT374CTSOC | ACTIVE | SOIC | DW | 20 | 25 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | |
| CY74FCT374CTSOCE4 | ACTIVE | SOIC | DW | 20 | 25 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | |
| CY74FCT374CTSOCG4 | ACTIVE | SOIC | DW | 20 | 25 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | |
| CY74FCT374TQCT | ACTIVE | SSOP | DBQ | 20 | 2500 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-2-260C-1 YEAR | |
| CY74FCT374TQCTE4 | ACTIVE | SSOP | DBQ | 20 | 2500 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-2-260C-1 YEAR | |
| CY74FCT374TQCTG4 | ACTIVE | SSOP | DBQ | 20 | 2500 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-2-260C-1 YEAR | |
| CY74FCT374TSOC | ACTIVE | SOIC | DW | 20 | 25 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | |
| CY74FCT374TSOCE4 | ACTIVE | SOIC | DW | 20 | 25 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | |
| CY74FCT374TSOCG4 | ACTIVE | SOIC | DW | 20 | 25 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | |
| CY74FCT374TSOCT | ACTIVE | SOIC | DW | 20 | 2000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | |
| CY74FCT374TSOCTE4 | ACTIVE | SOIC | DW | 20 | 2000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | |
| CY74FCT374TSOCTG4 | ACTIVE | SOIC | DW | 20 | 2000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | |
| CY74FCT574ATQCT | ACTIVE | SSOP | DBQ | 20 | 2500 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-2-260C-1 YEAR | |

| Orderable Device | Status ⁽¹⁾ | Package Type | Package Drawing | Pins | Package Qty | Eco Plan ⁽²⁾ | Lead/ Ball Finish | MSL Peak Temp ⁽³⁾ | Samples (Requires Login) |
|--------------------|-----------------------|--------------|-----------------|------|-------------|-------------------------|----------------------|------------------------------|-----------------------------|
| CY74FCT574ATQCTE4 | ACTIVE | SSOP | DBQ | 20 | 2500 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-2-260C-1 YEAR | |
| CY74FCT574ATQCTG4 | ACTIVE | SSOP | DBQ | 20 | 2500 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-2-260C-1 YEAR | |
| CY74FCT574ATSOC | ACTIVE | SOIC | DW | 20 | 25 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | |
| CY74FCT574ATSOCE4 | ACTIVE | SOIC | DW | 20 | 25 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | |
| CY74FCT574ATSOCG4 | ACTIVE | SOIC | DW | 20 | 25 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | |
| CY74FCT574ATSOCT | ACTIVE | SOIC | DW | 20 | 2000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | |
| CY74FCT574ATSOCTE4 | ACTIVE | SOIC | DW | 20 | 2000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | |
| CY74FCT574ATSOCTG4 | ACTIVE | SOIC | DW | 20 | 2000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | |
| CY74FCT574CTQCT | ACTIVE | SSOP | DBQ | 20 | 2500 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-2-260C-1 YEAR | |
| CY74FCT574CTQCTE4 | ACTIVE | SSOP | DBQ | 20 | 2500 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-2-260C-1 YEAR | |
| CY74FCT574CTQCTG4 | ACTIVE | SSOP | DBQ | 20 | 2500 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-2-260C-1 YEAR | |
| CY74FCT574CTSOC | ACTIVE | SOIC | DW | 20 | 25 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | |
| CY74FCT574CTSOCE4 | ACTIVE | SOIC | DW | 20 | 25 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | |
| CY74FCT574CTSOCG4 | ACTIVE | SOIC | DW | 20 | 25 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | |
| CY74FCT574CTSOCT | ACTIVE | SOIC | DW | 20 | 2000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | |
| CY74FCT574CTSOCTE4 | ACTIVE | SOIC | DW | 20 | 2000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | |
| CY74FCT574CTSOCTG4 | ACTIVE | SOIC | DW | 20 | 2000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | |
| CY74FCT574TQCT | ACTIVE | SSOP | DBQ | 20 | 2500 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-2-260C-1 YEAR | |

| Orderable Device | Status ⁽¹⁾ | Package Type | Package Drawing | Pins | Package Qty | Eco Plan ⁽²⁾ | Lead/ Ball Finish | MSL Peak Temp ⁽³⁾ | Samples (Requires Login) |
|------------------|-----------------------|--------------|-----------------|------|-------------|-------------------------|----------------------|------------------------------|-----------------------------|
| CY74FCT574TQCTE4 | ACTIVE | SSOP | DBQ | 20 | 2500 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-2-260C-1 YEAR | |
| CY74FCT574TQCTG4 | ACTIVE | SSOP | DBQ | 20 | 2500 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-2-260C-1 YEAR | |
| CY74FCT574TSOC | ACTIVE | SOIC | DW | 20 | 25 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | |
| CY74FCT574TSOCE4 | ACTIVE | SOIC | DW | 20 | 25 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | |
| CY74FCT574TSOCG4 | ACTIVE | SOIC | DW | 20 | 25 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | |

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

⁽²⁾ Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

⁽³⁾ MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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TAPE AND REEL INFORMATION

REEL DIMENSIONS



TAPE DIMENSIONS



| | |
|----|---|
| A0 | Dimension designed to accommodate the component width |
| B0 | Dimension designed to accommodate the component length |
| K0 | Dimension designed to accommodate the component thickness |
| W | Overall width of the carrier tape |
| P1 | Pitch between successive cavity centers |

TAPE AND REEL INFORMATION

*All dimensions are nominal

| Device | Package Type | Package Drawing | Pins | SPQ | Reel Diameter (mm) | Reel Width W1 (mm) | A0 (mm) | B0 (mm) | K0 (mm) | P1 (mm) | W (mm) | Pin1 Quadrant |
|------------------|--------------|-----------------|------|------|--------------------|--------------------|---------|---------|---------|---------|--------|---------------|
| CY74FCT374ATQCT | SSOP | DBQ | 20 | 2500 | 330.0 | 16.4 | 6.5 | 9.0 | 2.1 | 8.0 | 16.0 | Q1 |
| CY74FCT374ATSOCT | SOIC | DW | 20 | 2000 | 330.0 | 24.4 | 10.8 | 13.0 | 2.7 | 12.0 | 24.0 | Q1 |
| CY74FCT374CTQCT | SSOP | DBQ | 20 | 2500 | 330.0 | 16.4 | 6.5 | 9.0 | 2.1 | 8.0 | 16.0 | Q1 |
| CY74FCT374TQCT | SSOP | DBQ | 20 | 2500 | 330.0 | 16.4 | 6.5 | 9.0 | 2.1 | 8.0 | 16.0 | Q1 |
| CY74FCT374TSOCT | SOIC | DW | 20 | 2000 | 330.0 | 24.4 | 10.8 | 13.0 | 2.7 | 12.0 | 24.0 | Q1 |
| CY74FCT574ATQCT | SSOP | DBQ | 20 | 2500 | 330.0 | 16.4 | 6.5 | 9.0 | 2.1 | 8.0 | 16.0 | Q1 |
| CY74FCT574ATSOCT | SOIC | DW | 20 | 2000 | 330.0 | 24.4 | 10.8 | 13.0 | 2.7 | 12.0 | 24.0 | Q1 |
| CY74FCT574CTQCT | SSOP | DBQ | 20 | 2500 | 330.0 | 16.4 | 6.5 | 9.0 | 2.1 | 8.0 | 16.0 | Q1 |
| CY74FCT574CTSOCT | SOIC | DW | 20 | 2000 | 330.0 | 24.4 | 10.8 | 13.0 | 2.7 | 12.0 | 24.0 | Q1 |
| CY74FCT574TQCT | SSOP | DBQ | 20 | 2500 | 330.0 | 16.4 | 6.5 | 9.0 | 2.1 | 8.0 | 16.0 | Q1 |

TAPE AND REEL BOX DIMENSIONS


*All dimensions are nominal

| Device | Package Type | Package Drawing | Pins | SPQ | Length (mm) | Width (mm) | Height (mm) |
|------------------|--------------|-----------------|------|------|-------------|------------|-------------|
| CY74FCT374ATQCT | SSOP | DBQ | 20 | 2500 | 367.0 | 367.0 | 38.0 |
| CY74FCT374ATSOCT | SOIC | DW | 20 | 2000 | 367.0 | 367.0 | 45.0 |
| CY74FCT374CTQCT | SSOP | DBQ | 20 | 2500 | 367.0 | 367.0 | 38.0 |
| CY74FCT374TQCT | SSOP | DBQ | 20 | 2500 | 367.0 | 367.0 | 38.0 |
| CY74FCT374TSOCT | SOIC | DW | 20 | 2000 | 367.0 | 367.0 | 45.0 |
| CY74FCT574ATQCT | SSOP | DBQ | 20 | 2500 | 367.0 | 367.0 | 38.0 |
| CY74FCT574ATSOCT | SOIC | DW | 20 | 2000 | 367.0 | 367.0 | 45.0 |
| CY74FCT574CTQCT | SSOP | DBQ | 20 | 2500 | 367.0 | 367.0 | 38.0 |
| CY74FCT574CTSOCT | SOIC | DW | 20 | 2000 | 367.0 | 367.0 | 45.0 |
| CY74FCT574TQCT | SSOP | DBQ | 20 | 2500 | 367.0 | 367.0 | 38.0 |

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